## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Ronald Redline, et al.

Serial No.:

09/698,370

Filed:

October 26, 2000

Docket No.:

2156-056A

Batch No.

Date of Mailing of Notice of

Allowance and Issue Fee:

Group Art Unit: 1741

April 12, 2002

Examiner: W. Nicolas

Title:

Method For Enhancing the Solderability Of A Surface

Box Issue Fee **Assistant Commissioner for Patents** Washington, D.C. 20231

## **AMENDMENT AFTER NOTICE OF ALLOWANCE UNDER 37 CFR 1.312**

Prior to payment of the issue fee, please amend the above-entitled application as follows:

## IN THE SPECIFICATION

Please delete the paragraphs on page 13, line 1 through page 15, line 5 and replace them with the following:

## EXAMPLE I

IPC-B-25 test circuit boards were processed with the following steps:

- Acid Cleaner, 5 minutes, 120°F a).
- Water Rinse b).
- Sodium persulfate/sulfuric acid microetch, 1 minute, 95°F c).
- Water rinse d).

(W1215694)